EE C245 – ME C218
Introduction to MEMS Design
Fall 2012

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Lecture Module 1: Admin & Overview

Instructor: Prof. Clark T.-C. Nguyen

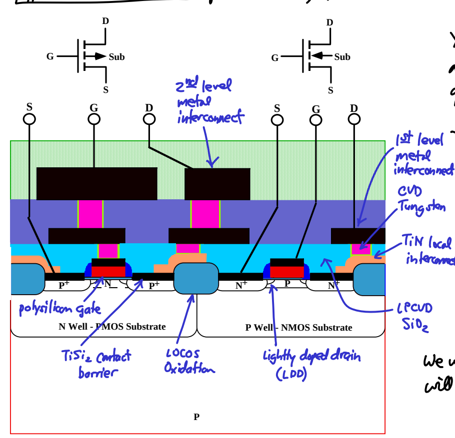
- *Education*: Ph.D., University of California at Berkeley, 1994
- *1995*: joined the faculty of the Dept. of EECS at the University of Michigan
- *2006*: (came back) joined the faculty of the Dept. of EECS at UC Berkeley
- *Research*: exactly the topic of this course, with a heavy emphasis on vibrating RF MEMS
- *Teaching*: (at the UofM) mainly transistor circuit design courses; (UC Berkeley) 140, 143, 243, 245
- *2001*: founded Discera, the first company to commercialize vibrating RF MEMS technology
- *Mid-2002 to 2005*: DARPA MEMS program manager
  - ran 10 different MEMS-based programs
  - *topics*: power generation, chip-scale atomic clock, gas analyzers, nuclear power sources, navigation-grade gyros, on-chip cooling, micro environmental control

Course Overview

- Goals of the course:
  - Accessible to a broad audience (minimal prerequisites)
  - Design emphasis
    - Exposure to the techniques useful in analytical design of structures, transducers, and process flows
  - Perspective on MEMS research and commercialization circa 2012
- Related courses at UC Berkeley:
  - EE 143: Microfabrication Technology
  - EE 147: Introduction to MEMS
  - ME 119: Introduction to MEMS (mainly fabrication)
  - BioEng 121: Introduction to Micro and Nano Biotechnology and BioMEMS
  - ME C219 – EE C246: MEMS Design
- Assumed background for EE C245: graduate standing in engineering or physical/bio sciences

What Should You Know?

Typical mid-2000's CMOS Process (good down to ~0.25μm)

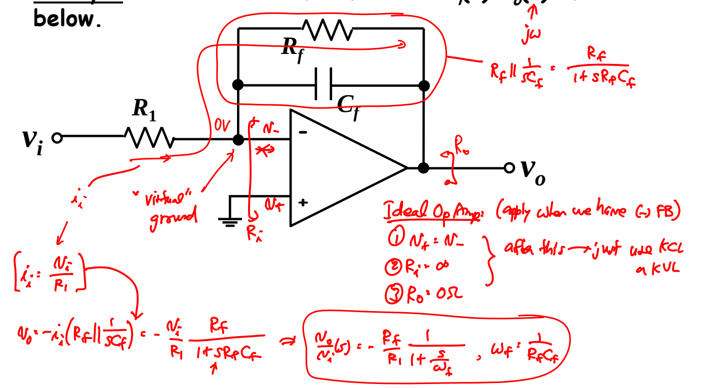


You should either already know or be able to learn independently & very quickly:
1. How to deposit or grow these different layers.
2. How to pattern or otherwise form the shapes of the layers shown.
3. What determines the order by which the different layers are formed, e.g., temperature limits, topography limits, etc...

We will review these things, but we will do this very fast!

What Should You Know?

- Basic circuit analysis & design using op amps
- *Example*: Find the transfer function $v_o(s)/v_i(s)$ of the circuit below.



Course Overview

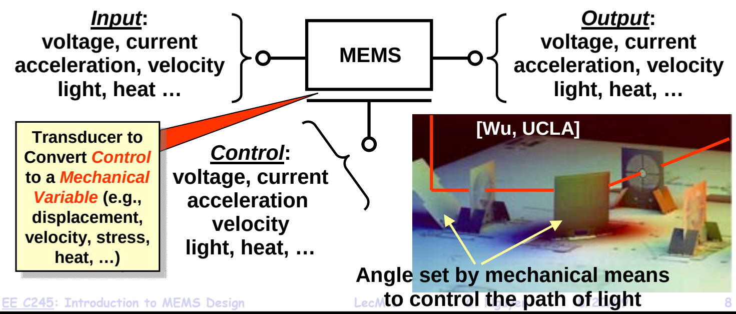
- The mechanics of the course are summarized in the course handouts, given out in lecture today
  - Course Information Sheet
    - Course description
    - Course mechanics
    - Textbooks
    - Grading policy
  - Syllabus
    - Lecture by lecture timeline w/ associated reading sections
    - Midterm Exam: tentatively set for Thursday, Oct. 25
    - Final Exam: Friday, Dec. 14, 7-10 p.m.
    - Project due date TBD (but near semester's end)

Lecture Outline

- Reading: Senturia, Chapter 1
- Lecture Topics:
  - Definitions for MEMS
  - MEMS roadmap
  - Benefits of Miniaturization

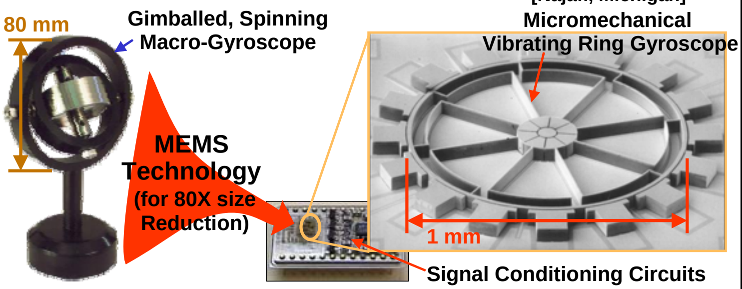
MEMS: Micro Electro Mechanical System

- A device constructed using micromachining (MEMS) tech.
- A micro-scale or smaller device/system that operates mainly via a mechanical or electromechanical means
- At least some of the signals flowing through a MEMS device are best described in terms of mechanical variables, e.g., displacement, velocity, acceleration, temperature, flow



Other Common Attributes of MEMS

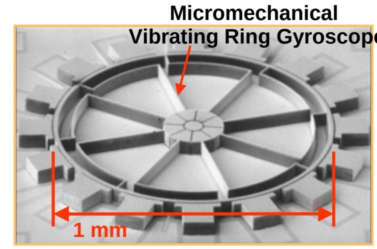
- Feature sizes measured in microns or less



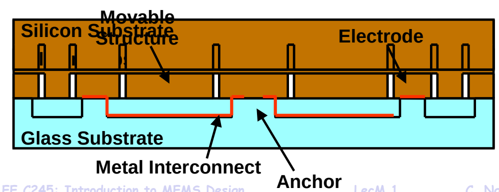
- Merges computation with sensing and actuation to change the way we perceive and control the physical world
- Planar lithographic technology often used for fabrication
  - can use fab equipment identical to those needed for IC's
  - however, some fabrication steps transcend those of conventional IC processing

Bulk Micromachining and Bonding

- Use the wafer itself as the structural material
- *Adv*: very large aspect ratios, thick structures
- *Example*: deep etching and wafer bonding

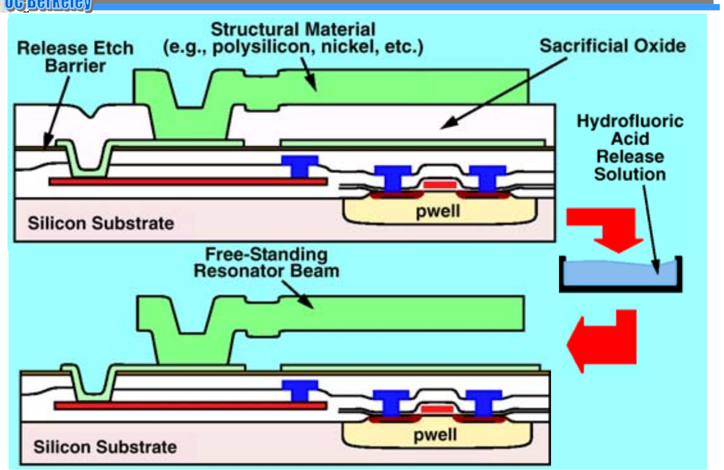


[Najafi, Michigan]



Microrotor
(for a microengine)

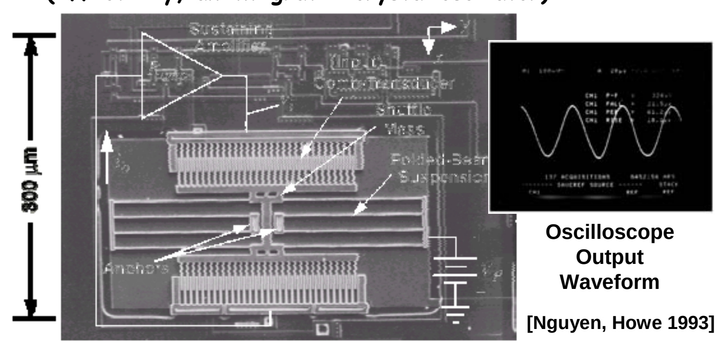
Surface Micromachining



- Fabrication steps compatible with planar IC processing

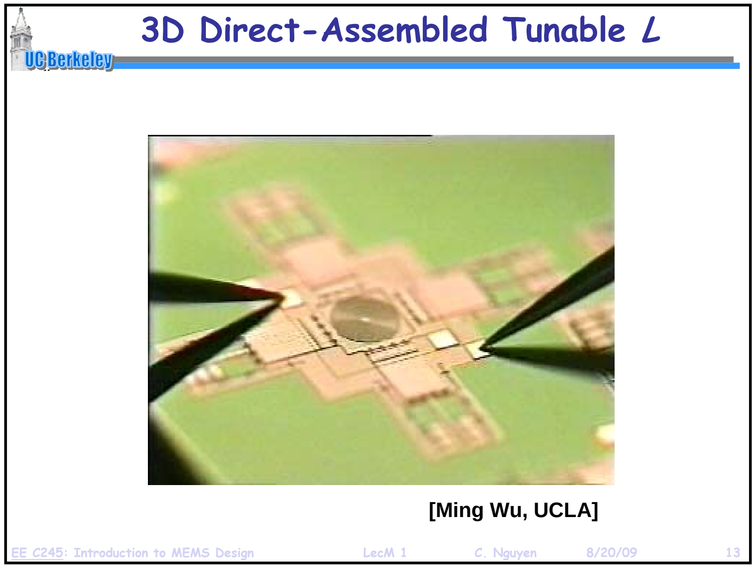
Single-Chip Ckt/MEMS Integration

- Completely monolithic, low phase noise, high-Q oscillator (effectively, an integrated crystal oscillator)



[Nguyen, Howe 1993]

- To allow the use of >600°C processing temperatures, tungsten (instead of aluminum) is used for metallization


3D Direct-Assembled Tunable L
UC Berkeley
[Ming Wu, UCLA]
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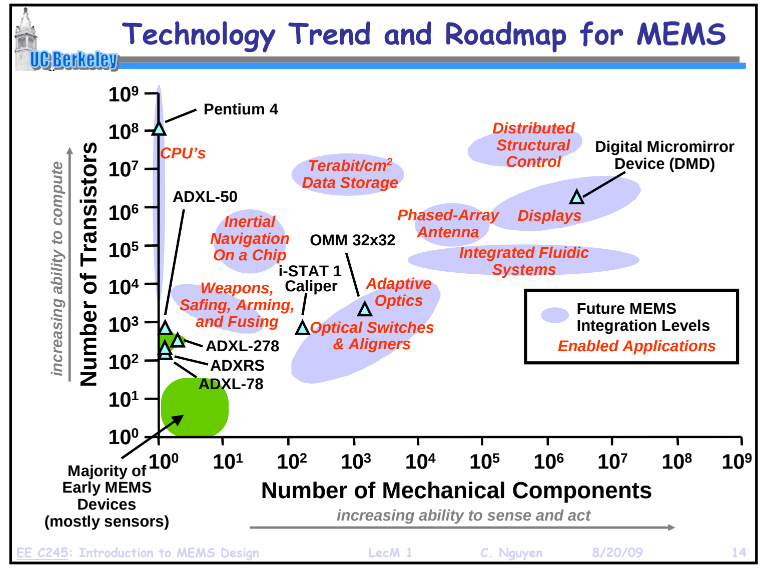
Technology Trend and Roadmap for MEMS
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Number of Transistors
increasing ability to compute
Number of Mechanical Components
increasing ability to sense and act
Pentium 4
CPU's
ADXL-50
ADXL-278
ADXRS
ADXL-78
Majority of Early MEMS Devices (mostly sensors)
Terabit/cm² Data Storage
Distributed Structural Control
Digital Micromirror Device (DMD)
Inertial Navigation On a Chip
OMM 32x32
Phased-Array Antenna
Displays
Integrated Fluidic Systems
i-STAT 1 Caliper
Weapons, Safing, Arming, and Fusing
Adaptive Optics
Optical Switches & Aligners
Future MEMS Integration Levels
Enabled Applications
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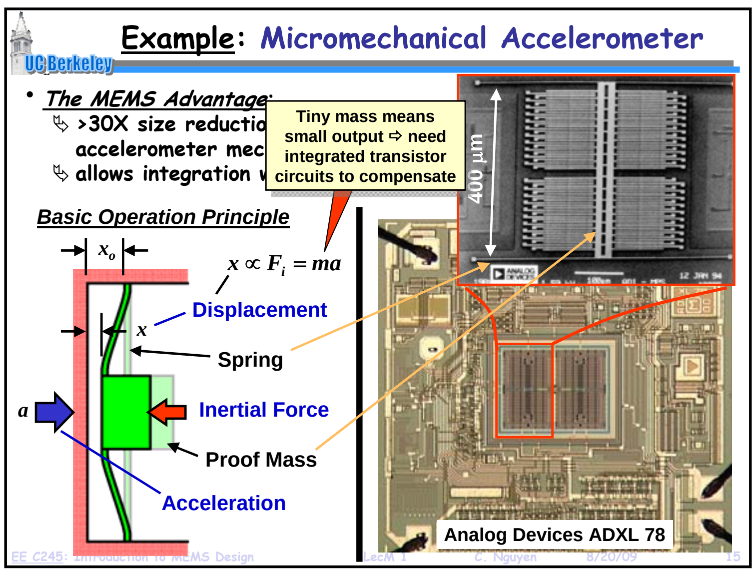
Example: Micromechanical Accelerometer
UC Berkeley
The MEMS Advantage:
>30X size reductio… accelerometer mec…
allows integration w…
Tiny mass means small output ⇨ need integrated transistor circuits to compensate
Basic Operation Principle
$x \propto F_i = ma$
Displacement
Spring
Inertial Force
Proof Mass
Acceleration
400 µm
Analog Devices ADXL 78
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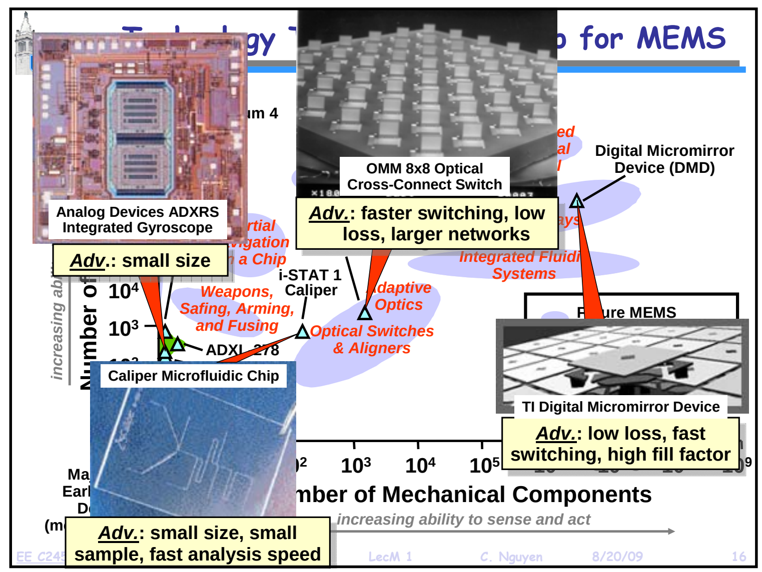
Technology Trend and Roadmap for MEMS
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Analog Devices ADXRS Integrated Gyroscope
Adv.: small size
OMM 8x8 Optical Cross-Connect Switch
Adv.: faster switching, low loss, larger networks
Caliper Microfluidic Chip
Adv.: small size, small sample, fast analysis speed
TI Digital Micromirror Device
Adv.: low loss, fast switching, high fill factor
Digital Micromirror Device (DMD)
Number of Mechanical Components
increasing ability to sense and act
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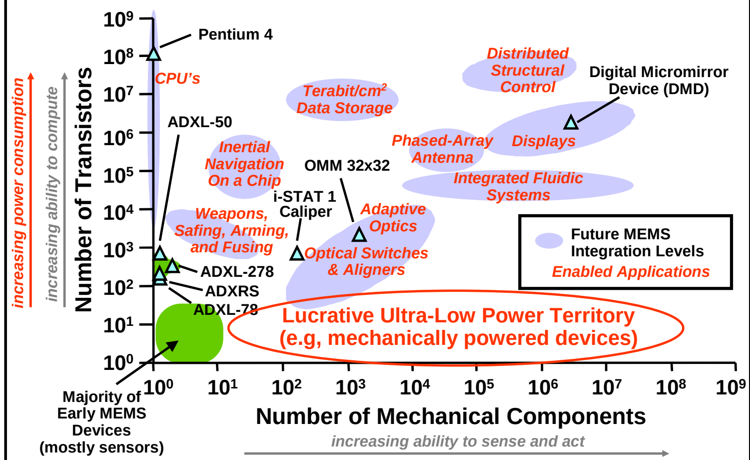
Technology Trend and Roadmap for MEMS



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Benefits of Size Reduction: MEMS

- Benefits of size reduction clear for IC's in elect. domain
  - size reduction ⇨ speed, low power, complexity, economy
- MEMS: enables a similar concept, but …

MEMS extends the benefits of size reduction *beyond* the electrical domain

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Performance enhancements for application domains beyond those satisfied by electronics in the same general categories

Speed	➡	Frequency ↑ , Thermal Time Const. ↓
Power Consumption	➡	Actuation Energy ↓ , Heating Power ↓
Complexity	➡	Integration Density ↑ , Functionality ↑
Economy	➡	Batch Fab. Pot. ↑ (esp. for packaging)
Robustness	➡	g-Force Resilience ↑

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